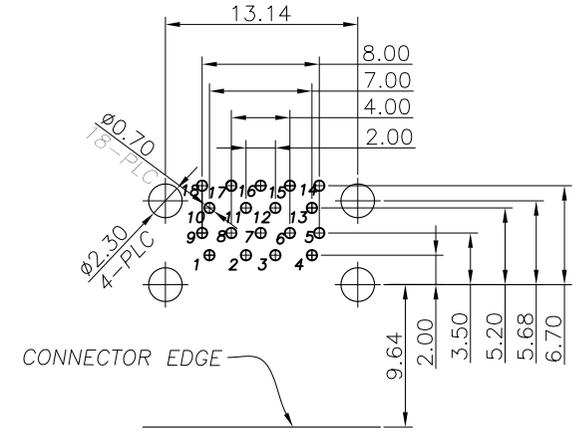
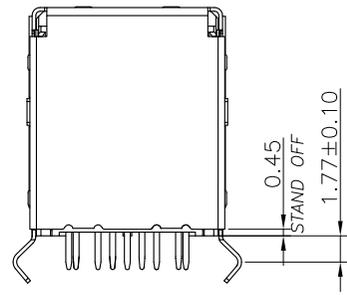
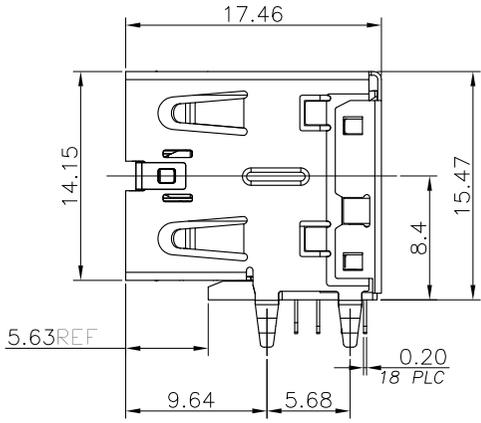
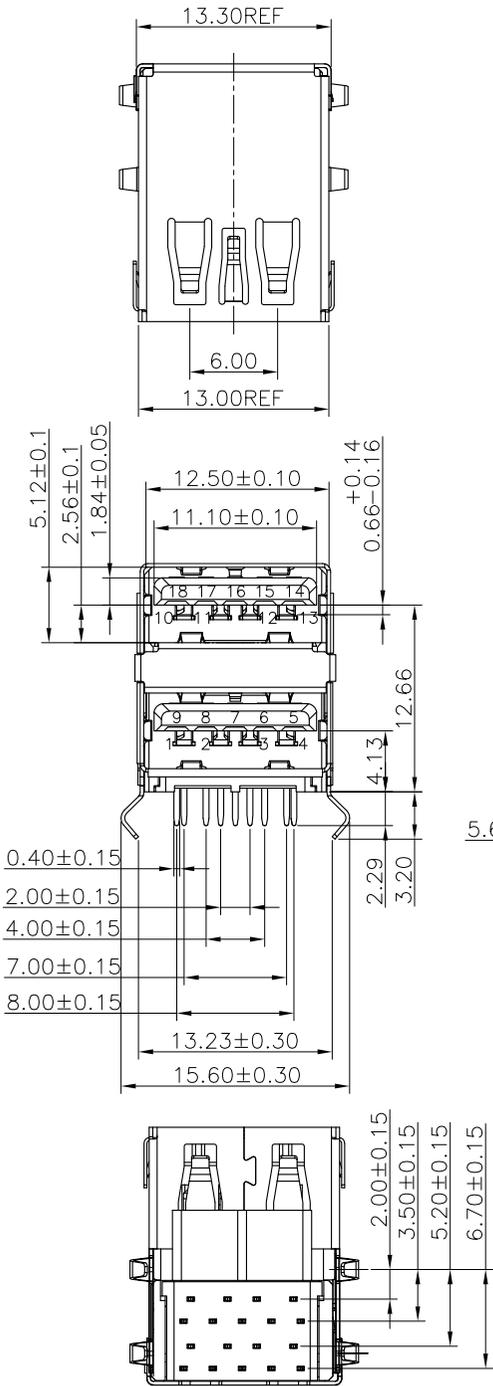


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2021/06/22	Ken Lin
A1			Change	2021/06/28	Ken Lin



RECOMMENDED PCB LAYOUT (TOP VIEW)
TOLERANCE: ±0.05mm

- NOTES:
- MATERIAL:
 - HOUSING: LCP UL 94V-0, COLOR: BLUE
 - 2.0 CONTACT: C2680R-EH T=0.20mm
 - 3.0 CONTACT: C2680R-EH T=0.20mm
 - SHELL: SUS201 T=0.25mm
 - MIDDLE SHELL: SUS201 T=0.20mm
 - FINISH:
 - CONTACT: GOLD FLASH (0.6u" Min) ON CONTACT AREA, 100u" TIN PLATED ON SOLDER TALLS, 50u" MIN. NICKEL UNDERPLATING OVER ALL.
 - SHELL: 80u" MIN. NICKEL UNDERPLATING OVER ALL.
 - ELECTRICAL:
 - CONTACT RESISTANCE: 30 mΩ(MAX) INITIAL FOR VBUS AND GND CONTACTS 50 mΩ(MAX) INITIAL FOR OTHER CONTACTS
 - CURRENT RATING: 1.5Amps MAX PER PIN
 - DIELECTRIC WITHSTANDING VOLTAGE: 100V AC FOR 1 MINUTE.
 - INSULATION RESISTANCE: 1000 MΩ MIN

MATRIX PART NO:
MUSB 18 - 01 - 599

Matrix-USB Pin number Series Number

Gold Plating:
 01=Gold Flash(0.6u" MIN)
 15=15u"
 30=30u"

USB 2.0 CONTACT PINS			USB 3.0 CONTACT PINS		
Pin NUMBER	SIGNAL NAME		Pin NUMBER	SIGNAL NAME	
1	10	VBUS	5	14	StdA_SSRX-
2	11	D-	6	15	StdA_SSRX+
3	12	D+	7	16	GND_DRAIN
4	13	GND	8	17	StdA_SSTX-
Shell		Shield	9	18	StdA_SSTX+

Matrix Electronics Co.,Ltd

TOLERANCE: X: X ±0.35 X:X ±0.25 X:XX ±0.20 X:XXX ±0.10 ANGLE: ±3°	DESIGN BY : Ken Lin	DATE : 2021/06/28	PART NAME: USB 3.0 Double Stacked H=15.47mm CH=8.40mm	
	CHECKED BY: Janice Liu	DATE : 2021/06/28	PART NO. MUSB18-01-599	MOLD NO. NA
UNIT: mm [inch] SCALE:1:1 SIZE:A4	APPROVED BY1: Richard Hsieh	DATE : 2021/06/28	DRAW NO.	SHEET NO. 1 OF 1
	APPROVED BY2: Richard Hsieh	DATE : 2021/06/28		